

150V N-Channel Radiation-Hardened MOSFET

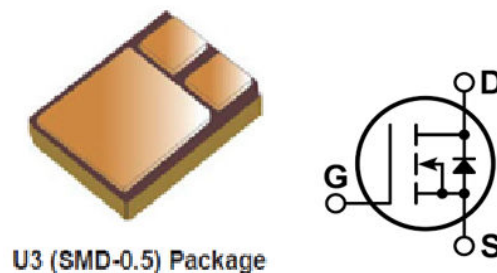
MRH15N19U3SR/JANSR2N7589U3



Product Overview

Microchip's new M6™ technology has been developed to provide extreme reliability and enhanced radiation hardness for hermetic Power MOSFETs targeted for space and military applications. Microchip Rad-Hard MOSFETs feature low $R_{DS(on)}$ and low total gate charge. The devices have been developed for Total Dose and Single-Event environments. M6 will perform in extreme-environment applications and will remain within specification in radiation environments up to 100 krad total ionizing dose (TID).

Figure 1. MRH15N19U3SR/JANSR2N7589U3



Features

The following are key features of the MRH15N19U3SR/JANSR2N7589U3 device:

- Low $R_{DS(on)}$
- Fast switching
- Single-event hardened
- Low gate charge
- Simple drive
- Ease of paralleling
- Hermetically sealed
- Surface-mount design
- Ceramic package
- ESD rating: Class 3B MIL-STD-750, TM 1020

Applications

The MRH15N19U3SR/JANSR2N7589U3 device is designed for the following applications:

- DC-DC converters
- Motor control
- Switch mode power supplies

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1. Electrical Specifications

This section shows the electrical specifications of the MRH15N19U3SR/JANSR2N7589U3 device.

1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MRH15N19U3SR/JANSR2N7589U3 device.

Table 1-1. Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-source voltage	150	V
I_D	Continuous drain current at $T_C = 25\text{ }^\circ\text{C}$	19	A
	Continuous drain current at $T_C = 100\text{ }^\circ\text{C}$	12.7	
I_{DM}	Pulsed drain current ¹	76	
V_{GS}	Gate-source voltage	± 20	V
dv/dt	Peak diode recovery	5.0	V/ns
P_D	Max. power dissipation at $T_C = 25\text{ }^\circ\text{C}$	75	W
	Linear derating factor	0.60	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating junction and storage temperature range	-55 to 150	$^\circ\text{C}$
T_L	Soldering temperature for 5 seconds (1.6 mm from case)	300	
Wt	Package weight	1.0 (typical)	g

Note:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

1.2 Electrical Performance

The following table shows the static characteristics of the MRH15N19U3SR/JANSR2N7589U3 device. $T_A = +25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 1-2. Static Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{BR(DSS)}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 1.0\text{ mA}$	150			V
$R_{DS(on)}$	Drain-source on resistance ¹	$V_{GS} = 12\text{ V}, I_D = 12\text{ A}$		0.07	0.088	Ω
$V_{GS(th)}$	Gate-source threshold voltage	$V_{GS} = V_{DS}, I_D = 1.0\text{ mA}$	2.0		4.0	V
g_{fs}	Forward transconductance	$V_{DS} = 15\text{ V}, I_{DS} = 12\text{ A}$	13			S
I_{DSS}	Zero-gate voltage drain current	$V_{DS} = 120\text{ V}$ $V_{GS} = 0\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		10	μA
			$T_A = 125\text{ }^\circ\text{C}$		25	
I_{GSS}	Gate-source leakage current	$V_{GS} = \pm 20\text{ V}$			± 100	nA

Note:

1. Pulse test: pulse width $< 300\text{ }\mu\text{s}$, duty cycle $< 2\%$.

The following table shows the dynamic characteristics of the MRH15N19U3SR/JANSR2N7589U3 device. $T_A = +25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 1-3. Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input capacitance	$V_{GS} = 0\text{ V}$		2140		pF
C_{rSS}	Reverse transfer capacitance	$V_{DS} = 25\text{ V}$		20		
C_{oss}	Output capacitance	$f = 1\text{ MHz}$		325		
Q_g	Total gate charge	$V_{GS} = 12\text{ V}$		32	50	nC
Q_{gs}	Gate-source charge	$I_D = 19\text{ A}$		13	15	
Q_{gd}	Gate-drain ("Miller") charge	$V_{DS} = 75\text{ V}$		5	20	

The following table shows the switching characteristics of the MRH15N19U3SR/JANSR2N7589U3 device.

Table 1-4. Switching Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	Time-on delay time	$V_{GS} = 12\text{ V}$		15	25	ns
t_r	Voltage rise time	$I_D = 19\text{ A}$		4	30	
$t_{d(off)}$	Time-off delay time	$V_{DS} = 75\text{ V}$		18	60	
t_f	Voltage fall time	$R_{G(ext)} = 7.5\ \Omega^1$		6	30	

Note:

1. R_G is the external gate resistance excluding internal gate driver impedance.

The following table shows the source-drain characteristics of the MRH15N19U3SR/JANSR2N7589U3 device. $T_A = +25\text{ °C}$ unless otherwise specified.

Table 1-5. Source-Drain Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_S	Continuous source current (body diode)	Integral reverse P-N junction diode			19	A
I_{SM}	Pulsed source current (body diode) ¹				76	
V_{SD}	Diode forward voltage ²	$I_{SD} = 19\text{ A}$ $T_A = 25\text{ °C}$ $V_{GS} = 0\text{ V}$			1.2	V
ESR	Gate equivalent source resistance	$F=1\text{ MHz}$ Level = 25 mV drain short		1.67		Ω
t_{rr}	Reverse recovery time	$I_F = 19\text{ A}$ $di/dt \leq 100\text{ A}/\mu\text{s}$ $V_{DD} \leq 50\text{ V}$			350	ns

Notes:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.
2. Pulse test: pulse width < 300 μs , duty cycle < 2%.

The following table shows the thermal resistance of the MRH15N19U3SR/JANSR2N7589U3 device.

Table 1-6. Thermal Resistance

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance			0.56	1.67	$^{\circ}\text{C}/\text{W}$

1.3 Typical Performance Curves

This section shows the typical performance curves of the MRH15N19U3SR/JANSR2N7589U3 device.

Figure 1-1. Output Characteristics at 25 °C

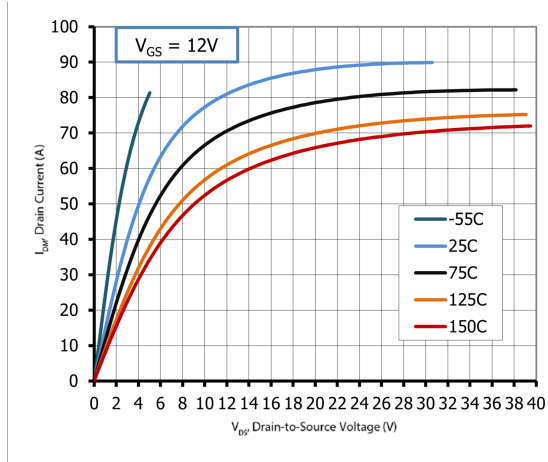


Figure 1-2. Output Characteristics at 150 °C

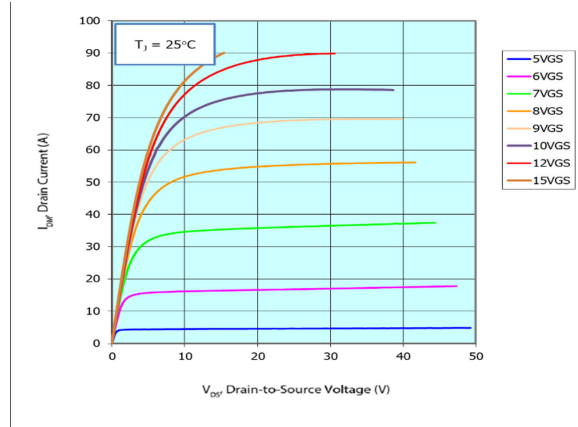


Figure 1-3. I_{DM} vs. V_{GS} at 25 °C and 150 °C

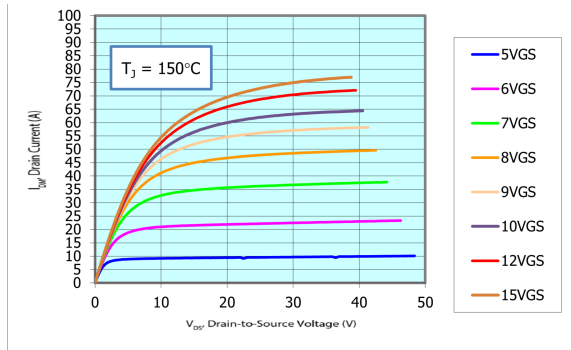


Figure 1-4. $R_{DS(on)}$ vs. Junction Temperature

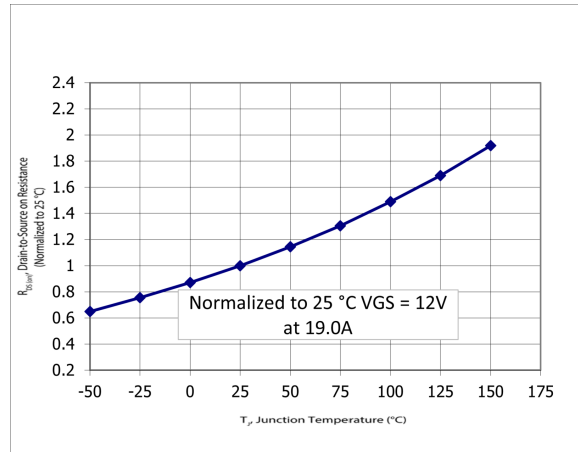


Figure 1-5. Q_C vs. V_{GS}

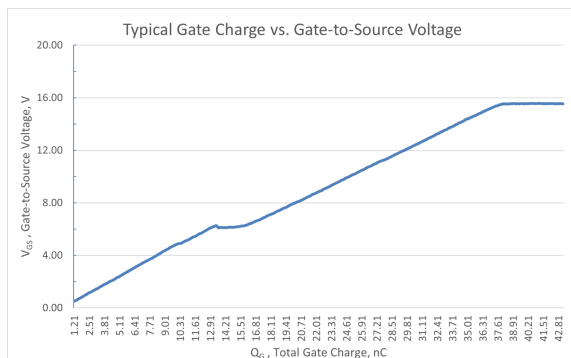


Figure 1-6. Capacitance vs. V_{DS}

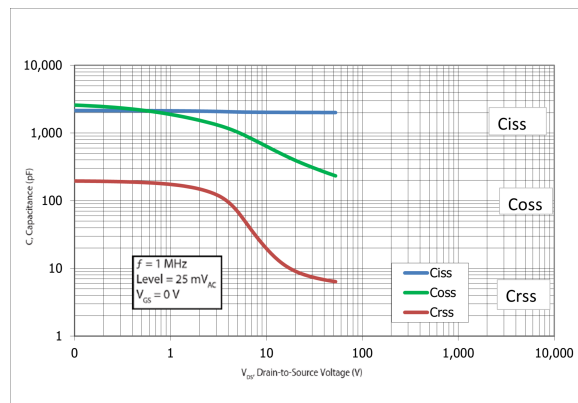


Figure 1-7. I_{DM} vs. V_{GS}

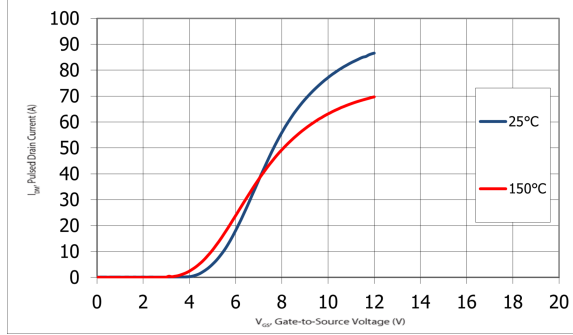


Figure 1-8. I_{DM} vs. V_{DS} 3rd Quadrant Conduction

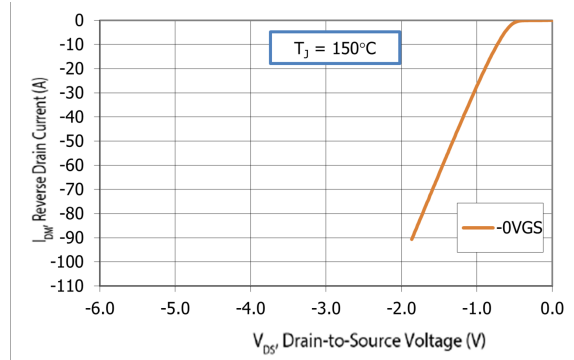


Figure 1-9. I_{DM} vs. V_{DS} 3rd Quadrant Conduction

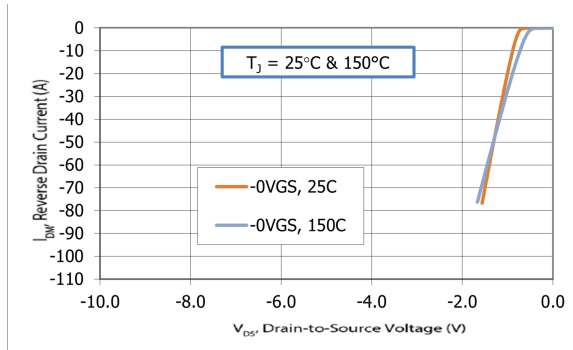


Figure 1-10. $V_{GS(th)}$ vs. Junction Temperature

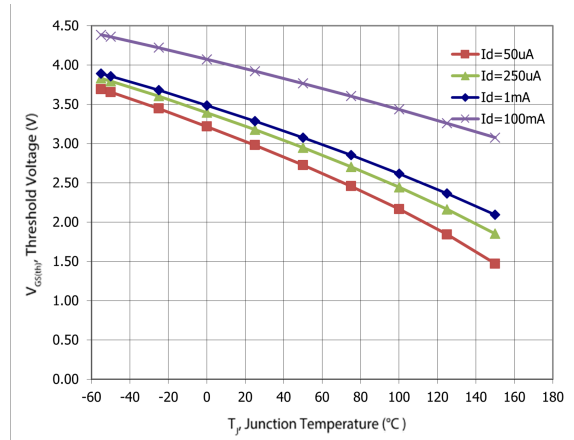


Figure 1-11. Forward Safe Operating Area

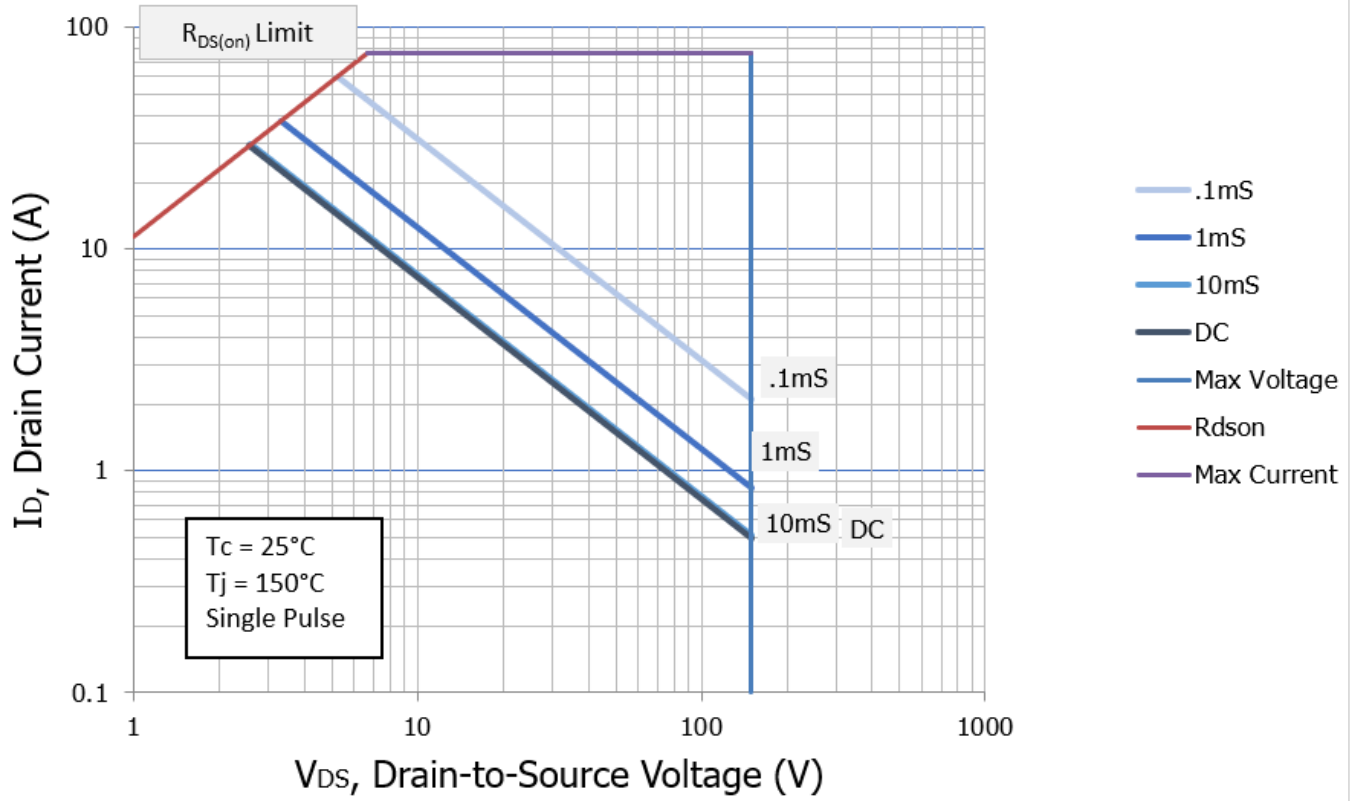


Figure 1-12. Maximum Transient Thermal Impedance

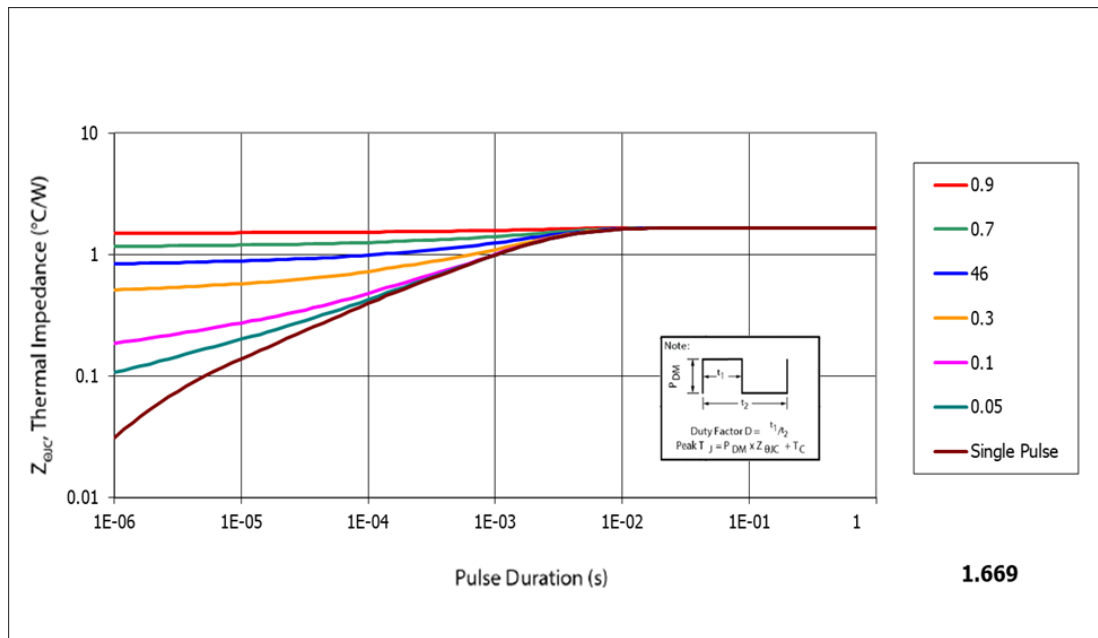


Figure 1-13. $R_{DS(on)}$ vs. Gate Voltage

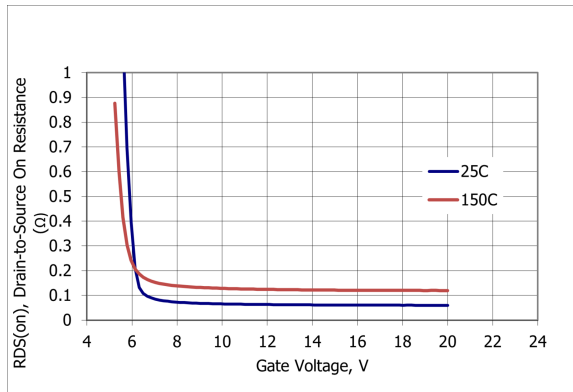


Figure 1-14. $R_{DS(on)}$ vs. Drain Current

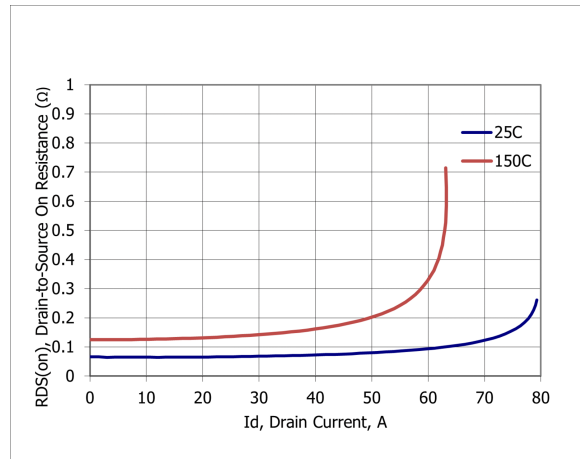
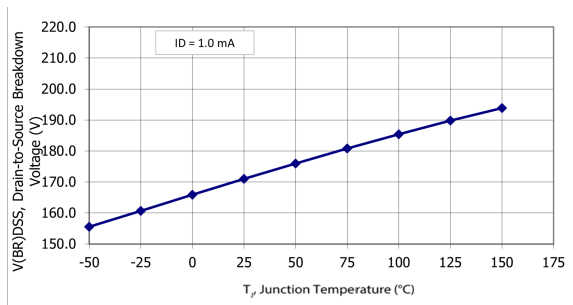


Figure 1-15. $V_{(BR)dss}$ vs. Junction Temperature



2. Single-Event Effects

The Microchip MRH15N19U3SR/JANSR2N7589U3 device has been characterized for heavy ion responses at the Texas A&M cyclotron. Devices have been characterized up to $V_{DS} = 150\text{ V}$ and $V_{GS} = -20\text{ V}$. The following single-event effects (SEE) safe-operating area profile has been established using the ions, linear energy transfer (LET), range, and total energy conditions shown.

Table 2-1. Safe-Operating Area Profile

Parameter	Description	Environment		V_{DS} (V)				
		Ion Energy (MeV)	Eff Range (μm)	$V_{GS} = 0\text{ V}$	$V_{GS} = 5\text{ V}$	$V_{GS} = 10\text{ V}$	$V_{GS} = 15\text{ V}$	$V_{GS} = 20\text{ V}$
Ion species	Typical LET (MeV/(mg/cm ²))							
Kr	38.6 (39 \pm 5%)	410 (410 \pm 5%)	50.8 (50 \pm 5%)	150	150	150	150	150
Xe	64 (61 \pm 5%)	942 (825 \pm 5%)	69.6 (66 \pm 7.5%)	150	150	150	40	
Au	90 (90 \pm 5%)	1489 (1470 \pm 5%)	83.2 (80 \pm 5%)	50	50	30		

The following figure shows the safe-operating area of the MRH15N19U3SR/JANSR2N7589U3 device.

Figure 2-1. SEE Safe-Operating Area

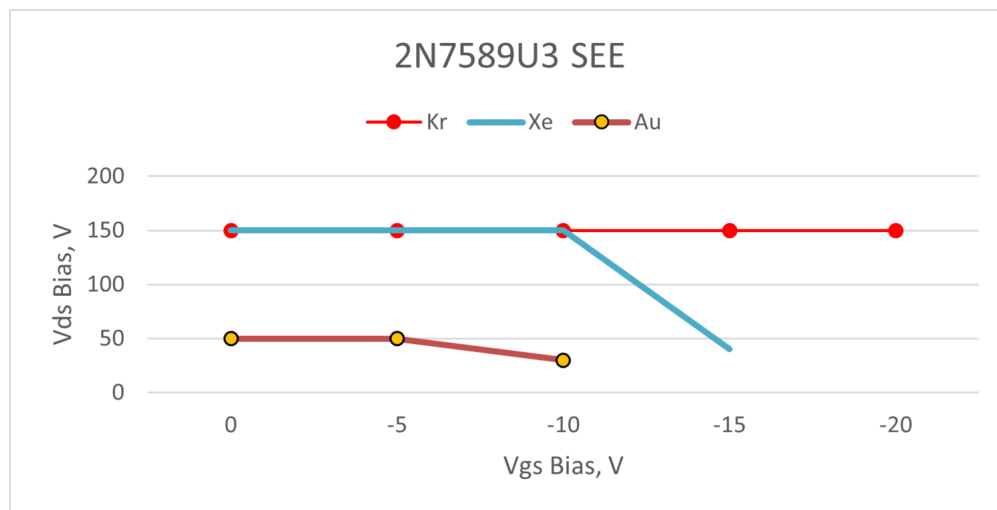
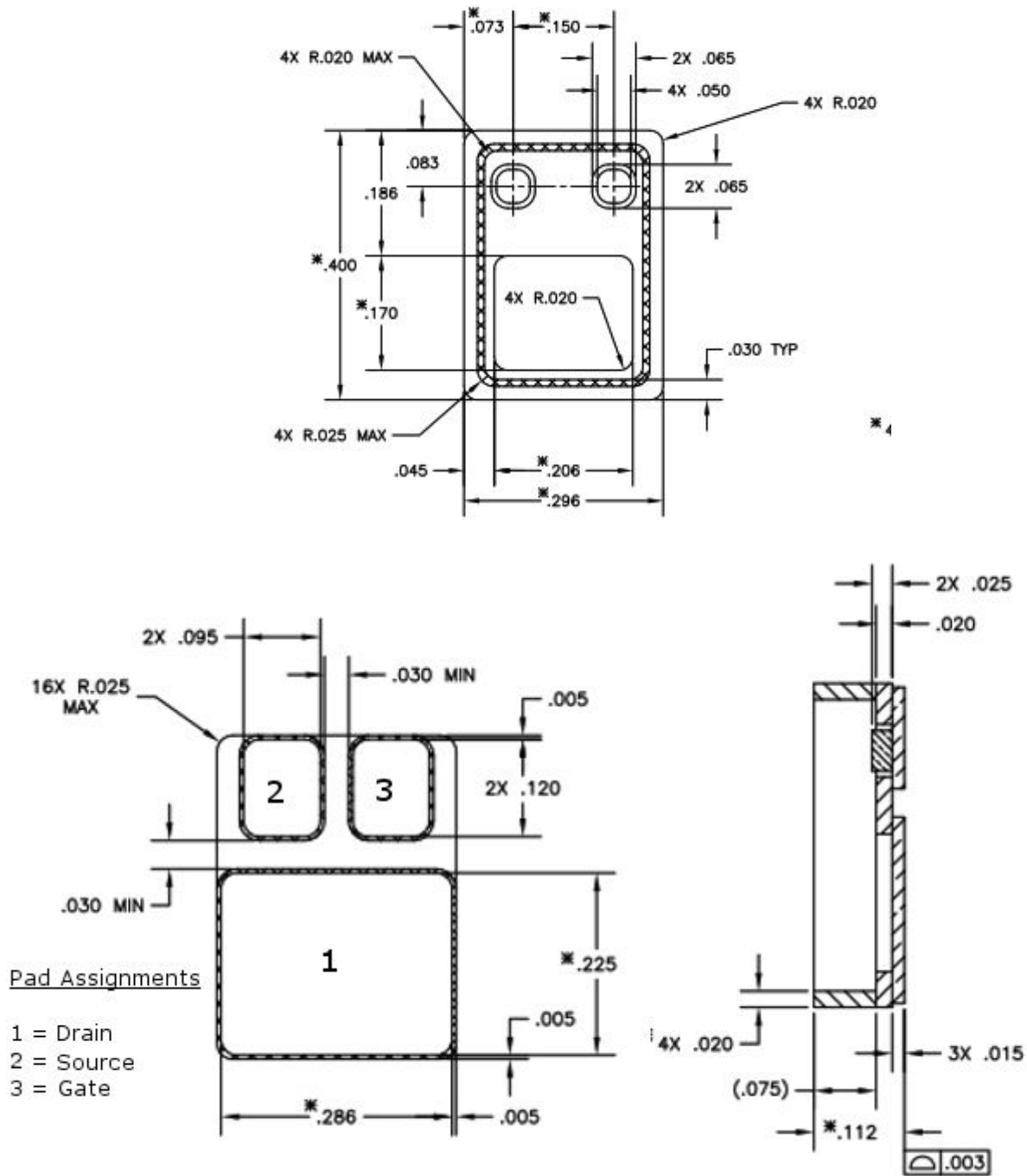


Figure 2-2. SMD.0 Case Outline and Dimensions



Microchip radiation-hardened MOSFETs are tested in a manner to provide maximum observability during heavy ion exposure. The filtering circuits of MIL-STD-750F Method 1080 are not used.

A V_{GS}/V_{DS} point is accepted on the prior plot if all of the following conditions are met:

1. A fluence of $3 \times 10^5 \pm 20\%$ ions/cm² is delivered to each sample.
2. No single-event burnout is detected via continuous monitoring of the drain current.
3. No single-event gate rupture is detected via continuous monitoring of the gate current.

4. Post-exposure IDSS tests continue to pass specification.
5. Post-exposure IGSS tests continue to pass specification.
6. Three randomly selected samples from different production lots are used for observation.

It should be noted that total energy levels are considered to be a factor in SEE characterization. Comparisons to other data sets should not be based on LET alone.

3. Revision History

Revision Level	Date	Description
B	8/2023	Updated Figure 1-11 Forward Safe Operating Area.
A	11/2022	Document created.

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